

5. Principle of Operation

5.1. Mechanical Parameters

Characteristics	Min	Unit
Creepage distances	5.0	mm
Clearance	5.0	
Internal isolation thickness	0.4	

6. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$)

	Characteristics	Symbol	Note	Rating	Unit
LED	Input forward current	I_F		50	mA
	Input forward current derating ($T_a \geq 90\text{ }^{\circ}\text{C}$)	$\Delta I_F / \Delta T_a$		-1.43	mA/ $^{\circ}\text{C}$
	Input forward current (pulsed)	I_{FP}	(Note 1)	1	A
	Input reverse voltage	V_R		5	V
	Input power dissipation	P_D		100	mW
	Input power dissipation derating ($T_a \geq 90\text{ }^{\circ}\text{C}$)	$\Delta P_D / \Delta T_a$		-2.86	mW/ $^{\circ}\text{C}$
	Junction temperature	T_j		125	$^{\circ}\text{C}$
Detector	Collector-emitter voltage	V_{CEO}		300	V
	Emitter-collector voltage	V_{ECO}		0.3	
	Collector current	I_C		150	mA
	Collector power dissipation	P_C		150	mW
	Collector power dissipation derating ($T_a \geq 25\text{ }^{\circ}\text{C}$)	$\Delta P_C / \Delta T_a$		-1.5	mW/ $^{\circ}\text{C}$
	Junction temperature	T_j		125	$^{\circ}\text{C}$
Common	Operating temperature	T_{opr}		-55 to 110	$^{\circ}\text{C}$
	Storage temperature	T_{stg}		-55 to 125	
	Lead soldering temperature (10 s)	T_{sol}		260	
	Total power dissipation	P_T		200	mW
	Isolation voltage AC, 60 s, R.H. $\leq 60\%$	BV_S	(Note 2)	3750	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width (PW) $\leq 100\text{ }\mu\text{s}$, $f = 1000\text{ Hz}$

Note 2: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.

7. Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$)

	Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
LED	Input forward voltage	V_F		$I_F = 10\text{ mA}$	1.1	1.25	1.4	V
	Input reverse current	I_R		$V_R = 5\text{ V}$	—	—	10	μA
	Input capacitance	C_t		$V = 0\text{ V}, f = 1\text{ MHz}$	—	30	—	pF
Detector	Collector-emitter breakdown voltage	$V_{(BR)CEO}$		$I_C = 0.1\text{ mA}$	300	—	—	V
	Emitter-collector breakdown voltage	$V_{(BR)ECO}$		$I_E = 0.1\text{ mA}$	0.3	—	—	V
	Dark Current	I_{DARK}		$V_{CE} = 200\text{ V}$	—	0.01	0.2	μA
				$V_{CE} = 200\text{ V}, T_a = 85\text{ }^{\circ}\text{C}$	—	—	20	μA
	Collector-emitter capacitance	C_{CE}		$V = 0\text{ V}, f = 1\text{ MHz}$	—	12	—	pF

8. Coupled Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Current transfer ratio	I_C/I_F		$I_F = 1\text{ mA}, V_{CE} = 1\text{ V}$	1000	4000	—	%
Saturated current transfer ratio	$I_C/I_{F(sat)}$		$I_F = 10\text{ mA}, V_{CE} = 1\text{ V}$	500	—	—	%
Collector-emitter saturation voltage	$V_{CE(sat)}$		$I_C = 10\text{ mA}, I_F = 1\text{ mA}$	—	—	1.0	V
			$I_C = 100\text{ mA}, I_F = 10\text{ mA}$	0.3	—	1.2	V
OFF-state collector current	$I_{C(off)}$		$V_F = 0.7\text{ V}, V_{CE} = 200\text{ V}$	—	—	20	μA

9. Isolation Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$)

Characteristics	Symbol	Note	Test Conditions	Min	Typ.	Max	Unit
Total capacitance (input to output)	C_S	(Note 1)	$V_S = 0\text{ V}, f = 1\text{ MHz}$	—	0.8	—	pF
Isolation resistance	R_S	(Note 1)	$V_S = 500\text{ V}, R.H. \leq 60\%$	10^{12}	10^{14}	—	Ω
Isolation voltage	BV_S	(Note 1)	AC, 60 s	3750	—	—	Vrms

Note 1: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.

10. Switching Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Rise time	t_r		$V_{CC} = 10\text{ V}, I_C = 10\text{ mA}, R_L = 100\text{ }\Omega$	—	40	—	μs
Fall time	t_f			—	15	—	
Turn-on time	t_{on}			—	50	—	
Turn-off time	t_{off}			—	15	—	
Turn-on time	t_{on}		See Figure 10.1	—	5	—	μs
Storage time	t_s		$R_L = 180\text{ }\Omega, V_{CC} = 10\text{ V}, I_F = 16\text{ mA}$	—	40	—	
Turn-off time	t_{off}			—	80	—	

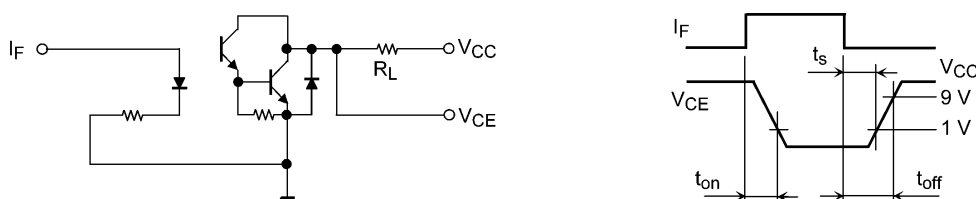


Fig. 10.1 Switching Time Test Circuit and Waveform

11. Characteristics Curves (Note)

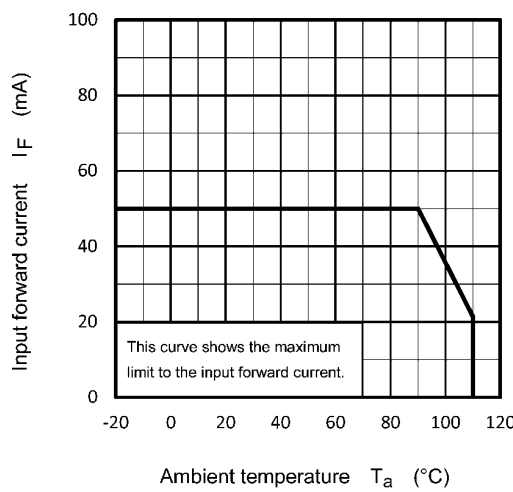


Fig. 11.1 $I_F - T_a$

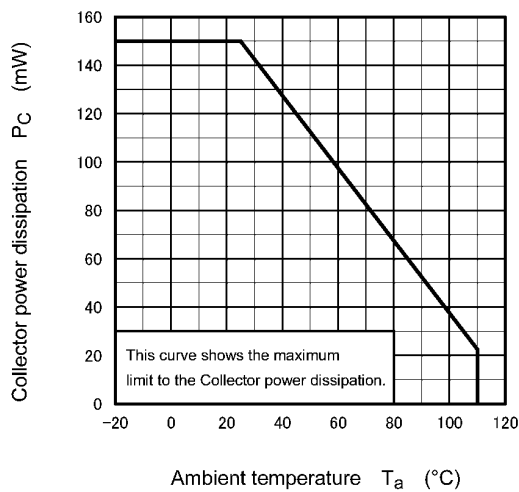


Fig. 11.2 $P_C - T_a$

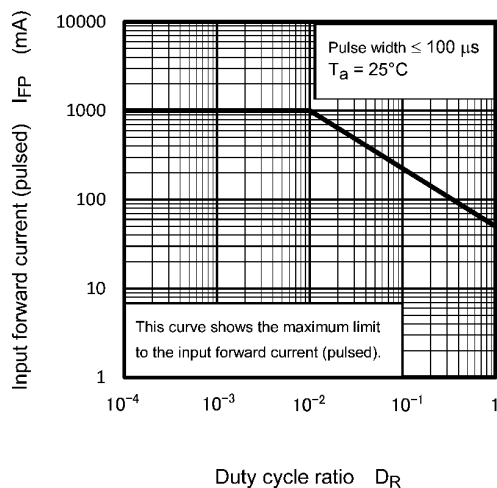


Fig. 11.3 $I_{FP} - D_R$

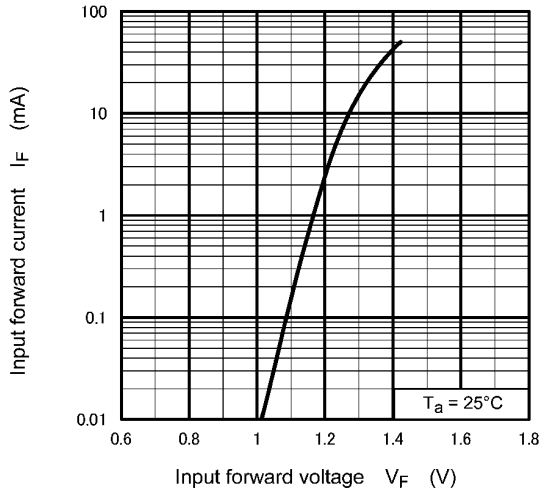


Fig. 11.4 $I_F - V_F$

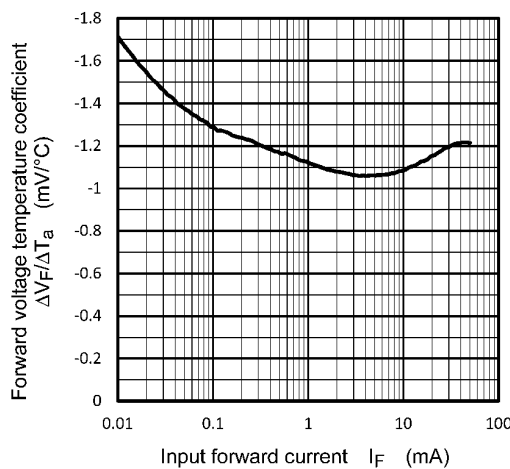


Fig. 11.5 $\Delta V_F / \Delta T_a - I_F$

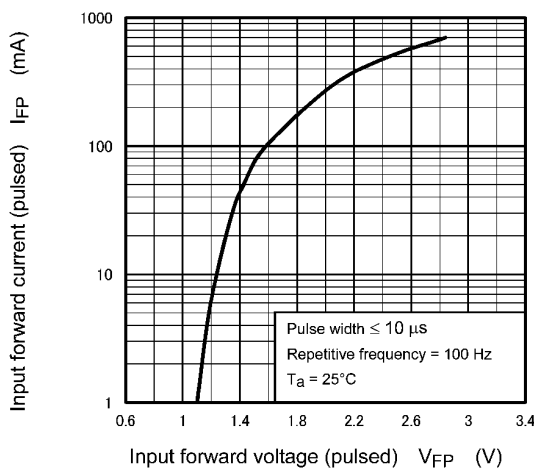


Fig. 11.6 $I_{FP} - V_{FP}$

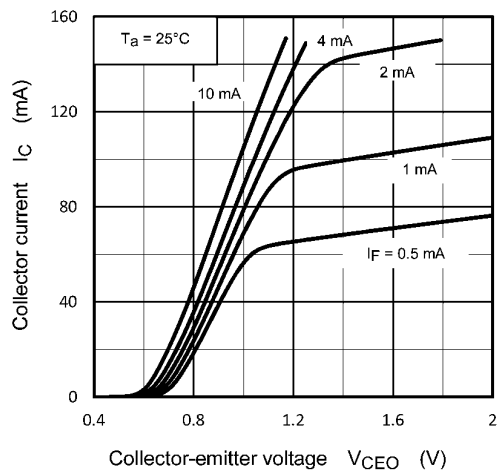


Fig. 11.7 IC - VCE0

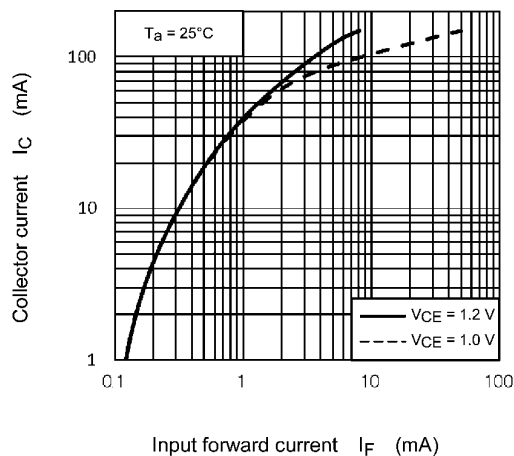


Fig. 11.8 IC - IF

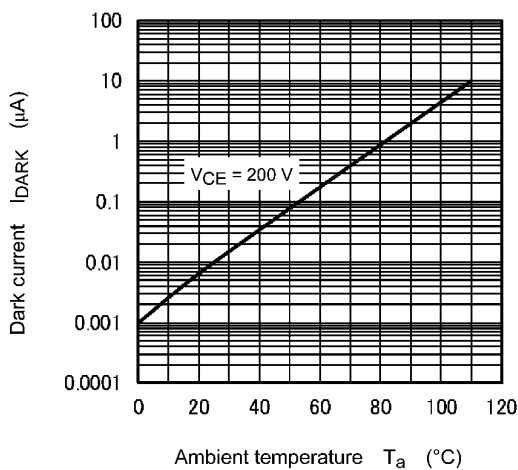


Fig. 11.9 IDARK - Ta

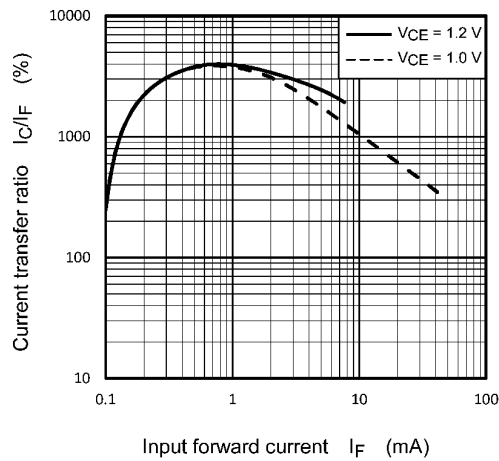


Fig. 11.10 IC/IF - IF

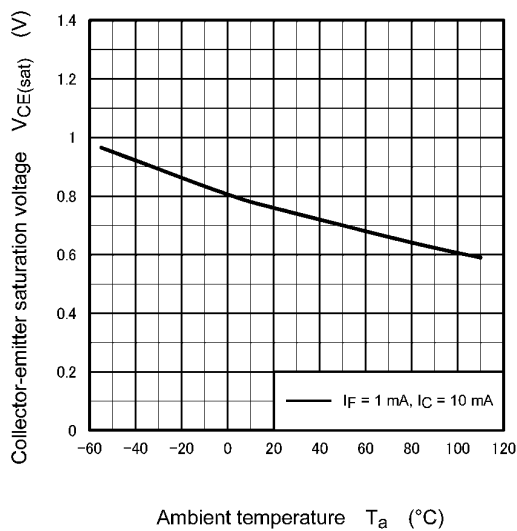


Fig. 11.11 VCE(sat) - Ta

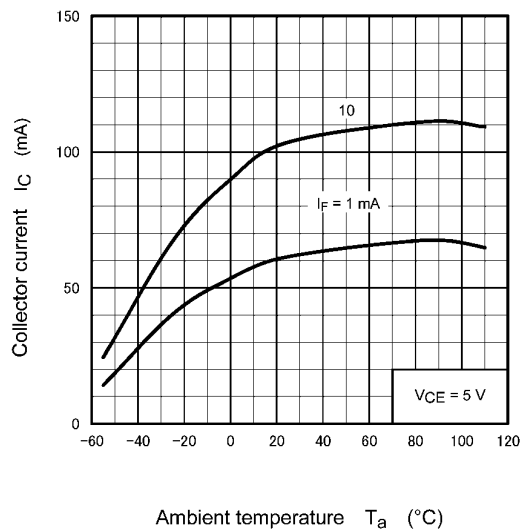


Fig. 11.12 IC - Ta

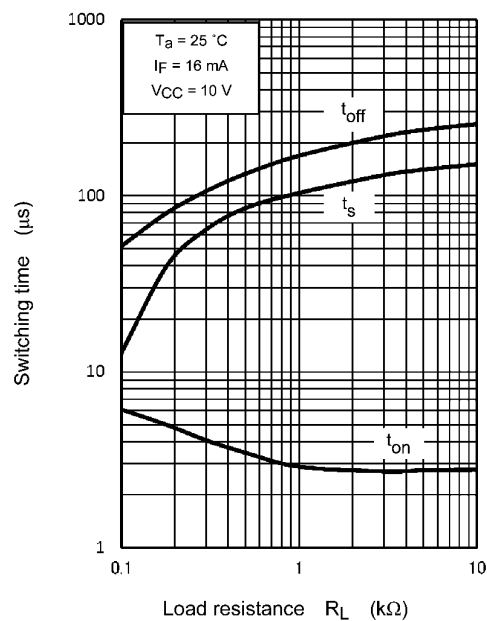


Fig. 11.13 Switching Time - R_L

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

12. Soldering and Storage

12.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

- When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.
(See the figure shown below, which is based on the package surface temperature.)
Reflow soldering must be performed once or twice.
The mounting should be completed with the interval from the first to the last mountings being 2 weeks.

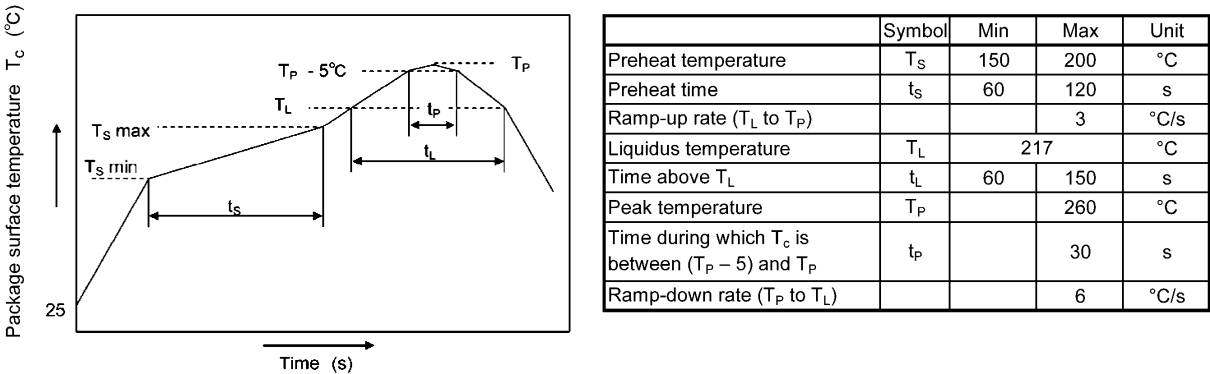


Fig. 12.1.1 An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

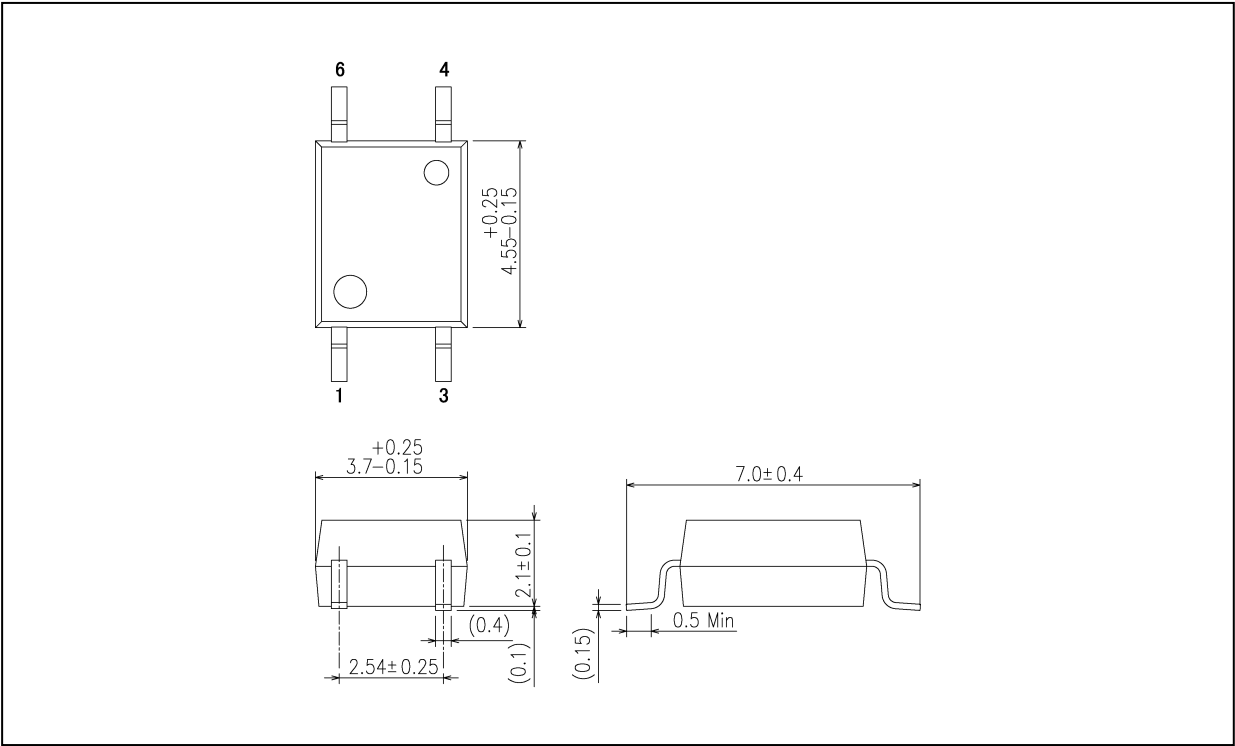
- When using soldering flow
Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.
Mounting condition of 260 °C within 10 seconds is recommended.
Flow soldering must be performed once.
- When using soldering Iron
Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C
Heating by soldering iron must be done only once per lead.

12.2. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

Package Dimensions

Unit: mm



Weight: 0.08 g (typ.)

Package Name(s)
TOSHIBA: 11-4M1S

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